




PCN Number:	20130503000			PCN Date:	05/16/2013															
Title:	Alternate Assembly Site for Selected Commercial CDIP Products																			
Customer Contact:	PCN Manager	Phone:	+1(214)480-6037	Dept:	Quality Services															
Proposed 1st Ship Date:	08/16/2013	Estimated Sample Availability:	05/16/2013																	
Change Type:																				
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials															
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification															
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process															
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process															
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process															
PCN Details																				
Description of Change:																				
Qualification of Millennium Microtech, Thailand (ALP) as an alternate Assembly site for selected commercial products in ceramic packages.																				
<table border="1"> <thead> <tr> <th></th> <th>AP1</th> <th>ALP</th> </tr> </thead> <tbody> <tr> <td>Mount Compound</td> <td>101182803</td> <td>039090034</td> </tr> <tr> <td>Bond Wire/Dia</td> <td>Al, 1.25mil</td> <td>Al, 1.25mil</td> </tr> <tr> <td>Lid</td> <td>203021501</td> <td>203021501</td> </tr> <tr> <td>Lead Finish</td> <td>SnPb</td> <td>SnPb</td> </tr> </tbody> </table>							AP1	ALP	Mount Compound	101182803	039090034	Bond Wire/Dia	Al, 1.25mil	Al, 1.25mil	Lid	203021501	203021501	Lead Finish	SnPb	SnPb
	AP1	ALP																		
Mount Compound	101182803	039090034																		
Bond Wire/Dia	Al, 1.25mil	Al, 1.25mil																		
Lid	203021501	203021501																		
Lead Finish	SnPb	SnPb																		
Reason for Change:																				
Continuity of Supply																				
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):																				
None																				
Changes to product identification resulting from this PCN:																				
Sample Product Shipping Label (not actual product label)																				
Assembly Site																				
AK1		Assembly Site Origin (22L)		ASO: AKR																
ALP		Assembly Site Origin (22L)		ASO: ALP																
  																				
MADE IN: Malaysia 2DC: 2Q:		MSL '2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04		(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO:USA (22L) ASO: MLA (23L) ACO: MYS																
OPT: 39 ITEM: LBL: 5A (L)T0:1750																				
Topside Device marking:																				
Assembly site code for AP1 = 4																				
Assembly site code for ALP = 8																				

Product Affected:

DS16F95AJA	LM124JBLK	LM158AJ	LM5116WG/NOPB
LF147J	LM139AJ/PB	LM158J	LM741J
LM101AJ	LM139AJBLK	LM158J/SL103829	LM95172EWG
LM111J-8	LM139J/PB	LM224J	LM95172EWG/NOPB
LM119J	LM139JBLK	LM239J	LMC6042AIJ
LM124AJ/PB	LM148J/PB	LM324J	LMC6042AJ
LM124AJBLK	LM148JBLK	LM339J	LMH6732J
LM124J/PB			

Reference Qualification Data: Approved April 2013

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qualification Device: LM124AJRLQMLV**Package Construction Details**

Assembly Site:	ALP	Mount Compound:	039090034
# Pins-Designator, Family:	14-J, CDIP	Lid:	203021501
Lead Finish:	SnPb	Bond Wire:	Al, 1.25mil

Qualification: Plan Test Results

Reliability Test	Conditions	Sample Size / Fail
Operating Life (125C, 1000hrs)	MIL-STD-883H, Method 1005	45/0
Moisture Resistance	MIL-STD-883H, Method 1004	15/0
Salt Atmosphere	MIL-STD-883H, Method 1009	15/0
Thermal Shock (-55/125)	MIL-STD-883H, Method 1011	15/0
Temp Cycle (-55/125)	MIL-STD-883H, Method 1010	15/0
Solder ability	MIL-STD-883H, Method 2003	22/0
Constant Acceleration	MIL-STD-883H, Method 2001	pass
Mechanical Shock	MIL-STD-883H, Method 2012	pass
Physical Dimensions	MIL-STD-883H, Method 2016	pass
Lead Integrity	MIL-STD-883H, Method 2004	pass
Lid Torque	MIL-STD-883H, Method 2024	pass
Bond Strength	MIL-STD-883H, Method 2011	pass
Die Shear	MIL-STD-883H, Method 2019	pass
Mark Permeability	MIL-STD-883H, Method 2015	pass
IGA	MIL-STD-883H, Method 1018	pass

Reference Qualification Data: Approved April 2013

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qualification Device: LMH6702JFQMLV**Package Construction Details**

Assembly Site:	ALP	Mount Compound:	039090034
# Pins-Designator, Family:	8-NAB, CDIP	Lid:	203021501
Lead Finish:	SnPb	Bond Wire:	Al, 1.25mil

Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results		
Reliability Test	Conditions	Sample Size / Fail
Operating Life (125C, 1000hrs)	MIL-STD-883H, Method 1005	45/0
Moisture Resistance	MIL-STD-883H, Method 1004	15/0
Salt Atmosphere	MIL-STD-883H, Method 1009	15/0
Thermal Shock (-55/125)	MIL-STD-883H, Method 1011	15/0
Temp Cycle (-55/125)	MIL-STD-883H, Method 1010	15/0
Solder ability	MIL-STD-883H, Method 2003	22/0
Constant Acceleration	MIL-STD-883H, Method 2001	pass
Mechanical Shock	MIL-STD-883H, Method 2012	pass
Physical Dimensions	MIL-STD-883H, Method 2016	pass
Lead Integrity	MIL-STD-883H, Method 2004	pass
Lid Torque	MIL-STD-883H, Method 2024	pass
Bond Strength	MIL-STD-883H, Method 2011	pass
Die Shear	MIL-STD-883H, Method 2019	pass
IGA	MIL-STD-883H, Method 1018	pass
Reference Qualification Data: Approved April 2013		
This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.		
Qualification Device: LM6142AMJ-QML		
Package Construction Details		
Assembly Site:	ALP	Mount Compound: 039090034
# Pins-Designator, Family:	8-NAB, CDIP	Lid: 203021501
Lead Finish:	SnPb	Bond Wire: Al, 1.25mil
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results		
Reliability Test	Conditions	Sample Size / Fail
Operating Life (125C, 1000hrs)	MIL-STD-883H, Method 1005	45/0
Moisture Resistance	MIL-STD-883H, Method 1004	15/0
Salt Atmosphere	MIL-STD-883H, Method 1009	15/0
Thermal Shock (-55/125)	MIL-STD-883H, Method 1011	15/0
Temp Cycle (-55/125)	MIL-STD-883H, Method 1010	15/0
Solder ability	MIL-STD-883H, Method 2003	22/0
Constant Acceleration	MIL-STD-883H, Method 2001	pass
Mechanical Shock	MIL-STD-883H, Method 2012	pass
Physical Dimensions	MIL-STD-883H, Method 2016	pass
Lead Integrity	MIL-STD-883H, Method 2004	pass
Lid Torque	MIL-STD-883H, Method 2024	pass
Bond Strength	MIL-STD-883H, Method 2011	pass
Mark Permeability	MIL-STD-883H, Method 2015	pass
IGA	MIL-STD-883H, Method 1018	pass

Reference Qualification Data: Approved April 2013

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qualification Device: LMD18200-2D/883**Package Construction Details**

Assembly Site:	ALP	Mount Compound:	039090034
# Pins-Designator, Family:	24-NAZ, CDIP	Lid:	203021501
Lead Finish:	SnPb	Bond Wire:	Al, 1.25mil

Qualification: Plan Test Results

Reliability Test	Conditions	Sample Size / Fail
Operating Life (125C, 1000hrs)	MIL-STD-883H, Method 1005	45/0
Moisture Resistance	MIL-STD-883H, Method 1004	15/0
Salt Atmosphere	MIL-STD-883H, Method 1009	15/0
Thermal Shock (-55/125)	MIL-STD-883H, Method 1011	15/0
Temp Cycle (-55/125)	MIL-STD-883H, Method 1010	15/0
Solder ability	MIL-STD-883H, Method 2003	22/0
Constant Acceleration	MIL-STD-883H, Method 2001	pass
Mechanical Shock	MIL-STD-883H, Method 2012	pass
Physical Dimensions	MIL-STD-883H, Method 2016	pass
Lead Integrity	MIL-STD-883H, Method 2004	pass
Bond Strength	MIL-STD-883H, Method 2011	pass
Mark Permeability	MIL-STD-883H, Method 2015	pass
IGA	MIL-STD-883H, Method 1018	pass

Reference Qualification Data: Approved April 2013

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qualification Device: LF444MD/883**Package Construction Details**

Assembly Site:	ALP	Mount Compound:	039090034
# Pins-Designator, Family:	14-NAK, CDIP	Lid:	203021501
Lead Finish:	SnPb	Bond Wire:	Al, 1.25mil

Qualification: Plan Test Results

Reliability Test	Conditions	Sample Size / Fail
Operating Life (125C, 1000hrs)	MIL-STD-883H, Method 1005	45/0
Moisture Resistance	MIL-STD-883H, Method 1004	15/0
Salt Atmosphere	MIL-STD-883H, Method 1009	15/0
Thermal Shock (-55/125)	MIL-STD-883H, Method 1011	15/0
Temp Cycle (-55/125)	MIL-STD-883H, Method 1010	15/0
Solder ability	MIL-STD-883H, Method 2003	22/0
Constant Acceleration	MIL-STD-883H, Method 2001	pass
Mechanical Shock	MIL-STD-883H, Method 2012	pass
Physical Dimensions	MIL-STD-883H, Method 2016	pass
Lead Integrity	MIL-STD-883H, Method 2004	pass
Bond Strength	MIL-STD-883H, Method 2011	pass
Mark Permeability	MIL-STD-883H, Method 2015	pass
IGA	MIL-STD-883H, Method 1018	pass

Reference Qualification Data: Approved April 2013			
This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.			
Qualification Device: LM117E/883			
Package Construction Details			
Assembly Site:	ALP	Mount Compound:	039090034
# Pins-Designator, Family:	20-NAJ, CDIP	Lid:	203021501
Lead Finish:	SnPb	Bond Wire:	Al, 1.25mil
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results			
Reliability Test	Conditions	Sample Size / Fail	
Operating Life (125C, 1000hrs)	MIL-STD-883H, Method 1005	45/0	
Moisture Resistance	MIL-STD-883H, Method 1004	15/0	
Salt Atmosphere	MIL-STD-883H, Method 1009	15/0	
Thermal Shock (-55/125)	MIL-STD-883H, Method 1011	15/0	
Temp Cycle (-55/125)	MIL-STD-883H, Method 1010	15/0	
Solder ability	MIL-STD-883H, Method 2003	22/0	
Constant Acceleration	MIL-STD-883H, Method 2001	pass	
Mechanical Shock	MIL-STD-883H, Method 2012	pass	
Physical Dimensions	MIL-STD-883H, Method 2016	pass	
Lead Integrity	MIL-STD-883H, Method 2004	pass	
Lid Torque	MIL-STD-883H, Method 2024	pass	
Bond Strength	MIL-STD-883H, Method 2011	pass	
Mark Permeability	MIL-STD-883H, Method 2015	pass	
IGA	MIL-STD-883H, Method 1018	pass	
Reference Qualification Data: Approved April 2013			
This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.			
Qualification Device: LM723E/883			
Package Construction Details			
Assembly Site:	ALP	Mount Compound:	039090034
# Pins-Designator, Family:	20-NAJ, CDIP	Lid:	203021501
Lead Finish:	SnPb	Bond Wire:	Al, 1.25mil

Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results		
Reliability Test	Conditions	Sample Size / Fail
Operating Life (125C, 1000hrs)	MIL-STD-883H, Method 1005	45/0
Moisture Resistance	MIL-STD-883H, Method 1004	15/0
Salt Atmosphere	MIL-STD-883H, Method 1009	15/0
Thermal Shock (-55/125)	MIL-STD-883H, Method 1011	15/0
Temp Cycle (-55/125)	MIL-STD-883H, Method 1010	15/0
Solder ability	MIL-STD-883H, Method 2003	22/0
Constant Acceleration	MIL-STD-883H, Method 2001	pass
Mechanical Shock	MIL-STD-883H, Method 2012	pass
Physical Dimensions	MIL-STD-883H, Method 2016	pass
Lead Integrity	MIL-STD-883H, Method 2004	pass
Lid Torque	MIL-STD-883H, Method 2024	pass
Bond Strength	MIL-STD-883H, Method 2011	pass
Mark Permeability	MIL-STD-883H, Method 2015	pass
IGA	MIL-STD-883H, Method 1018	pass

Reference Qualification Data: Approved April 2013

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qualification Device: DS1776E/883

Package Construction Details

Assembly Site:	ALP	Mount Compound:	039090034
# Pins-Designator, Family:	28-FK, CDIP	Lid:	203021501
Lead Finish:	SnPb	Bond Wire:	Al, 1.25mil

Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results		
Reliability Test	Conditions	Sample Size / Fail
Operating Life (125C, 1000hrs)	MIL-STD-883H, Method 1005	45/0
Moisture Resistance	MIL-STD-883H, Method 1004	15/0
Salt Atmosphere	MIL-STD-883H, Method 1009	15/0
Thermal Shock (-55/125)	MIL-STD-883H, Method 1011	15/0
Temp Cycle (-55/125)	MIL-STD-883H, Method 1010	15/0
Solder ability	MIL-STD-883H, Method 2003	22/0
Constant Acceleration	MIL-STD-883H, Method 2001	pass
Mechanical Shock	MIL-STD-883H, Method 2012	pass
Physical Dimensions	MIL-STD-883H, Method 2016	pass
Lead Integrity	MIL-STD-883H, Method 2004	pass
Lid Torque	MIL-STD-883H, Method 2024	pass
Bond Strength	MIL-STD-883H, Method 2011	pass
Mark Permeability	MIL-STD-883H, Method 2015	pass
IGA	MIL-STD-883H, Method 1018	pass

Reference Qualification Data: Approved April 2013		
This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.		
Qualification Device: AR629AU9/883		
Package Construction Details		
Assembly Site:	ALP	Mount Compound: 039090034
# Pins-Designator, Family:	180-NAT, CDIP	Lid: 203021501
Lead Finish:	SnPb	Bond Wire: Al, 1.25mil
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results		
Reliability Test	Conditions	Sample Size / Fail
Operating Life (125C, 1000hrs)	MIL-STD-883H, Method 1005	45/0
Moisture Resistance	MIL-STD-883H, Method 1004	15/0
Salt Atmosphere	MIL-STD-883H, Method 1009	15/0
Thermal Shock (-55/125)	MIL-STD-883H, Method 1011	15/0
Temp Cycle (-55/125)	MIL-STD-883H, Method 1010	15/0
Solder ability	MIL-STD-883H, Method 2003	22/0
Constant Acceleration	MIL-STD-883H, Method 2001	pass
Mechanical Shock	MIL-STD-883H, Method 2012	pass
Physical Dimensions	MIL-STD-883H, Method 2016	pass
Lead Integrity	MIL-STD-883H, Method 2004	pass
Lid Torque	MIL-STD-883H, Method 2024	pass
Bond Strength	MIL-STD-883H, Method 2011	pass
Mark Permeability	MIL-STD-883H, Method 2015	pass
IGA	MIL-STD-883H, Method 1018	pass

Reference Qualification Data: Approved April 2013		
This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.		
Qualification Device: LMH6702WG-QMLV		
Package Construction Details		
Assembly Site:	ALP	Mount Compound: 039090034
# Pins-Designator, Family:	10-NAC, CDIP	Lid: 203021501
Lead Finish:	SnPb	Bond Wire: Al, 1.25mil

Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results		
Reliability Test	Conditions	Sample Size / Fail
Operating Life (125C, 1000hrs)	MIL-STD-883H, Method 1005	45/0
Moisture Resistance	MIL-STD-883H, Method 1004	15/0
Salt Atmosphere	MIL-STD-883H, Method 1009	15/0
Thermal Shock (-55/125)	MIL-STD-883H, Method 1011	15/0
Temp Cycle (-55/125)	MIL-STD-883H, Method 1010	15/0
Solder ability	MIL-STD-883H, Method 2003	22/0
Constant Acceleration	MIL-STD-883H, Method 2001	pass
Mechanical Shock	MIL-STD-883H, Method 2012	pass
Physical Dimensions	MIL-STD-883H, Method 2016	pass
Lead Integrity	MIL-STD-883H, Method 2004	pass
Lid Torque	MIL-STD-883H, Method 2024	pass
Bond Strength	MIL-STD-883H, Method 2011	pass
Die Shear	MIL-STD-883H, Method 2019	pass
IGA	MIL-STD-883H, Method 1018	pass

Reference Qualification Data: Approved April 2013

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qualification Device: LM1575J-ADJ-QML

Package Construction Details

Assembly Site:	ALP	Mount Compound:	039090034
# Pins-Designator, Family:	15-NFE, CDIP	Lid:	203021501
Lead Finish:	SnPb	Bond Wire:	Al, 1.25mil

Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results		
Reliability Test	Conditions	Sample Size / Fail
Operating Life (125C, 1000hrs)	MIL-STD-883H, Method 1005	45/0
Moisture Resistance	MIL-STD-883H, Method 1004	15/0
Salt Atmosphere	MIL-STD-883H, Method 1009	15/0
Thermal Shock (-55/125)	MIL-STD-883H, Method 1011	15/0
Temp Cycle (-55/125)	MIL-STD-883H, Method 1010	15/0
Solder ability	MIL-STD-883H, Method 2003	22/0
Constant Acceleration	MIL-STD-883H, Method 2001	pass
Mechanical Shock	MIL-STD-883H, Method 2012	pass
Physical Dimensions	MIL-STD-883H, Method 2016	pass
Lead Integrity	MIL-STD-883H, Method 2004	pass
Lid Torque	MIL-STD-883H, Method 2024	pass
Bond Strength	MIL-STD-883H, Method 2011	pass
IGA	MIL-STD-883H, Method 1018	pass

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com